

SUM36N20-54P-E3-VB Datasheet N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{(BR)DSS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)	
200	0.038 at $V_{GS} = 15 \text{ V}$	45	57	
	0.043 at V _{GS} = 10 V	40	57	

FEATURES

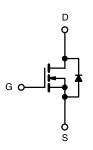
- Trench Power MOSFETS
- 175 °C Junction Temperature
- 100 % R_g and UIS Tested



APPLICATIONS

- Power Supply
- · Lighting Systems





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V _{DS}	V _{DS} 200			
Gate-Source Voltage		V _{GS}	± 25	V		
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 25 °C	I _D	45	Α		
Continuous Diam Current (1) = 175 C)	T _C = 100 °C	d' D	26			
Pulsed Drain Current		I _{DM}	150	^		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20			
Single Pulse Avalanche Energy ^a	L = 0.1 IIII1	E _{AS}	20	mJ		
Maximum Power Dissipation ^a	T _C = 25 °C	В	166 ^b	W		
	T _A = 25 °C ^c	$ P_D$	3.12			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) ^c	R_{thJA}	40	°C/W	
Junction-to-Case (Drain)	R_{thJC}	0.75]	

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current		V _{DS} = 200 V, V _{GS} = 0 V			1	
	I_{DSS}	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			Α
		$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.048		
Danie Course On Chata Besistance	R	V _{GS} = 10 V, I _D = 3 A, T _J = 125 °C		0.050		Ω
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 3 A, T _J = 175 °C		0.070		
		V _{GS} = 6 V, I _D = 3 A		0.092		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 3 A		35		S
Dynamic ^a						
Input Capacitance	C_{iss}			3000		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		180		
Reverse Transfer Capacitance	C _{rss}			80		
Total Gate Charge ^c	Q_g			34	51	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3 \text{ A}$		8		nC
Gate-Drain Charge ^c	Q_{gd}			12		
Gate Resistance	R_g		0.5		2.9	Ω
Turn-On Delay Time ^c	t _{d(on)}			15	25	
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_{L} = 5.2 \Omega$		50	75	ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	
Fall Time ^c	t _f			60	90	
Source-Drain Diode Ratings and Char	acteristics (7	T _C = 25 °C)				
Pulsed Current	I _{SM}				36	Α
Diode Forward Voltage ^b	V_{SD}	I _F = 3 A, V _{GS} = 0 V		0.9	1.5	V
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3 A, dI/dt = 100 A/μs		180	250	ns

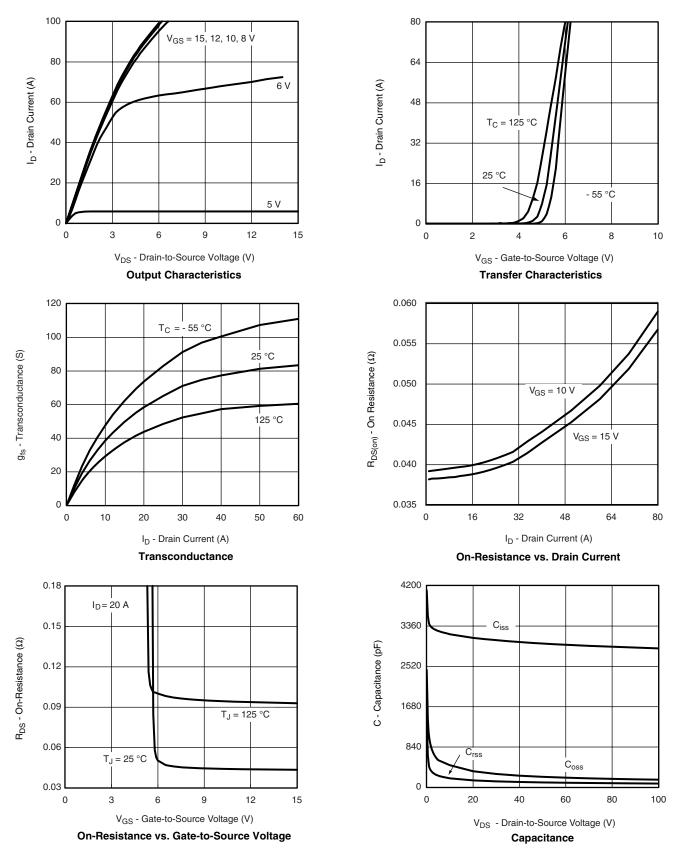
Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

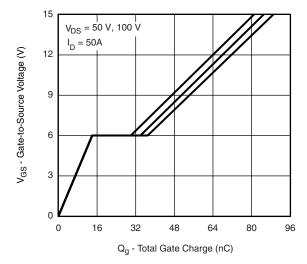


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

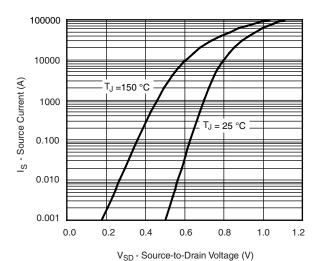




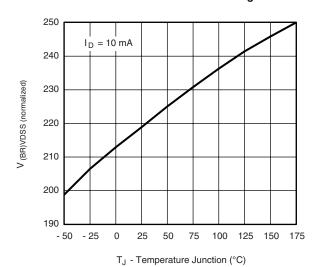
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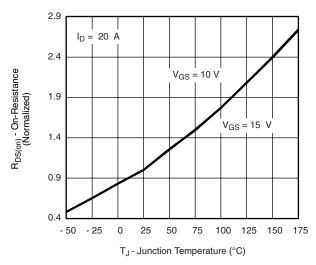
Gate Charge



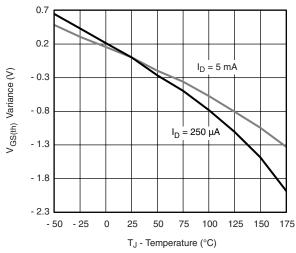
Source-Drain Diode Forward Voltage



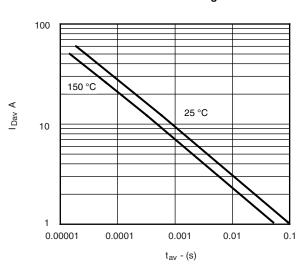
Drain Source Breakdown vs. Junction Temperature



On-Resistance vs. Junction Temperature



Threshold Voltage

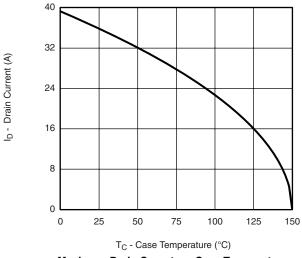


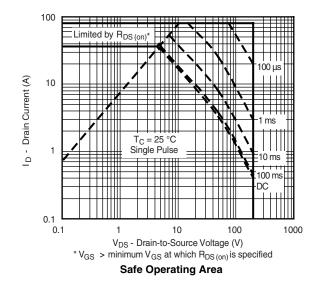
Single Pulse Avalanche Current Capability vs. Time

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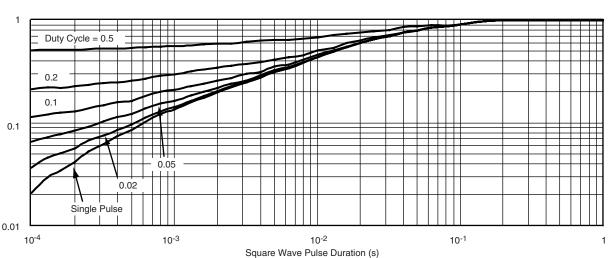


THERMAL RATINGS





Maximum Drain Curent vs. Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case

Normalized Effective Transient Thermal Impedance



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